



# MARKET FOCUS SESSIONS

# CALL FOR SPEAKERS

We are in our 17th year and we have become one of the highlights of the ECOC Exhibition and Technical conference attracting the world's best speakers from industry globally.

Every year the market focus is the key focus point of the show and has become a key event to get up-to-date knowledge from industry in key technical areas and latest commercial trends in optical communications. This year we have streamlined our market focus sessions that cover the whole value chain of technologies from optical components to optical network providers that span both telecommunications as well as datacenter/data communication media services. The market focus sessions for 2022 are divided into 5 categories with a session of 2 panels listed below.

Our advisory committee is composed of industry experts who will be reviewing submitted abstracts to plan another exciting live and in-person market focus event in Basel 2022.

Sponsored by:



Chaired by **Michael Lebby** from Lightwave Logic, the highly industrial and commercially experienced committee includes:

**Pierpaolo Ghiggino** Industry Consultant, **Wlodek Forysiak** of Aston University, **Stephan Neidlinger** from ADVA, **Daryl Inniss** from OFS, **Glenn Wellbrock** from Verizon, **Frank Chang** from Source Photonics, and **Bill Ring** from Voyant Photonics.

If you are interested in speaking at the ECOC Market Focus please visit [www.ecocexhibition.com/visit/market-focus/](http://www.ecocexhibition.com/visit/market-focus/) to submit your abstract stating your company name, position, topic of interest and a 100 word summary of your presentation theme with a title based on one of the topics below, by **Monday 13th June**.

## MARKET FOCUS 2022 TOPICS

### Service providers/media/social companies

1. Impact of social and media on the internet/network
2. State of the optical transport markets (metro, long haul, submarine) and OTN trends
3. Transmission roadmaps (route to 100s Tbps and associated MSAs/standards efforts)
4. Energy Efficient Ethernet and green datacenters
5. Power impact of co-packaging (CPO) vs. pluggable platforms
6. Scaling capacity and growth with DWDM super-channels
7. OTN Design & planning software
8. Embedded network monitoring, testing, and diagnostics
9. Intersatellite communication

### Networking/systems/DC/disaggregated solutions/software

1. Fibre access (5G) and next generation 6G/7G systems
2. Operator business models (regulation, standards, installation, mgt etc.)
3. High speed PON and FTTX solutions (cables, antennas, coherent etc.)
4. Future trends for server/switch designs and architectures in the datacenter
5. Network architectures and wavelength routing and gridless architectures
6. Colourless, directionless, contentionless ROADM networks
7. Network automation and SDN standards/industry groups
8. Network disaggregation: Open terminals, Optical Line Systems, white boxes

### Modules/sub-systems/connectors/line-cards

1. Advanced fiber-based connector/interfaces/panels
2. Competitive modules for WDM / high-speed PON
3. PIC based transceivers (pluggable and co-packaged/CPO)
4. Architecture trends for line cards, faceplate, rack data throughput
5. Intelligent sensors/sensing using fiber communications
6. Agile transceivers (data rate, wavelength, modulation scheme, coherent/coherent-lite, FEC, etc.)
7. Embedded optics/waveguides in pcbs and associated interposers
8. Chip-to-chip communications (fiber and/or optical wireless) Integrated (Black Box) vs. Disaggregated platforms
9. White box networking architectures/trends/technology platforms

### Components/ICs/PICs/fiber

1. Classic component performance (discrete and integrated photonics), ROADMs
2. High speed, low power modulators (polymer, TFLN, plasmonic, Silicon, InP etc.)
3. Tunable and fixed wavelength devices
4. Future PIC trends, roadmaps, complexity with InP, silicon photonics, polymers
5. VCSELS: high speed, arrays, smart pixels
6. Electronics (and associated modulation techniques - PAM, QPSK, QAM etc.) for lightwave (DSPs, ASICs, computational processing)
7. Advanced packaging trends (low cost, high speed, volume driven, CoB, FC, interposers) and associated testing techniques

### New and emerging technologies

1. 3D structured light and sensing
2. Transportation, remote, and distributed sensing
3. Optical radars or lidar
4. Bio-medical applications
5. POF (Plastic optical fibre) cabling/interconnect applications/testing
6. Satellite and free space optics
7. Automotive (LIDAR) sensing optics, beam steering, phased array optics
8. Ultra-short (<10m) distance data communications, AOC and parallel optics
9. Projection optics (home and cinema/conference applications)
10. Novel PICs and photonic devices/materials and platforms
11. Optical switching materials/components

### 2 roundtables/panels

1. The race decrease power consumption in the network
2. Pluggable optics vs co-packaging for 104Tbps+ and beyond platforms



THE ECOC EXHIBITION  
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[www.ecocexhibition.com](http://www.ecocexhibition.com)